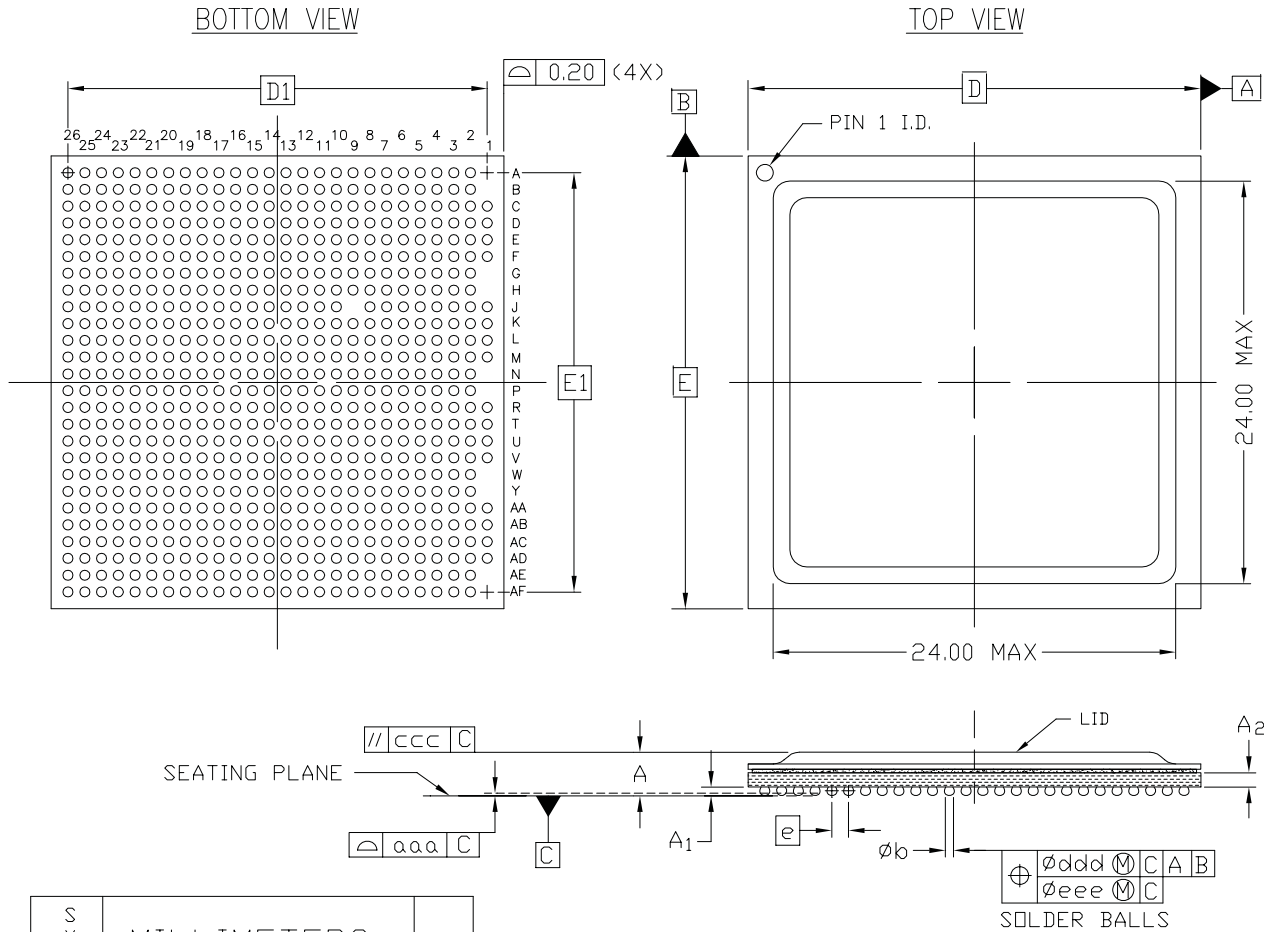


Flip-Chip BGA (FF665) Package



NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAL-1

665 BALL - FLIP-CHIP BGA (FF665)
27 X 27mm BODY (1.00mm PITCH)

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
3/22/07	1.0	Initial Xilinx release.